



**Response Under 37 C.F.R. § 1.116
Expedited Procedure
Examining Group 1746
PATENT**

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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In re the application of:)
R. Treur)
Application No: 09/823,813)
Filed: March 30, 2001)
For: ANGULAR SPIN, RINSE, AND)
DRY MODULE AND METHODS FOR)
MAKING AND IMPLEMENTING THE)
SAME)

Examiner: F. L. Stinson

NOV 28 2003

Group Art Unit: 1746

TC 1700

Date: November 18, 2003

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail addressed to: Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450 on November 18, 2003.

Signed: _____

Courtney F. Yadegar

Mail Box: AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

REQUEST FOR RECONSIDERATION

Dear Sir:

In response to the Final Office Action mailed on September 18, 2003, Applicant hereby submits this Request for Reconsideration. Please enter the following remarks in the above-identified patent application:

The listing of claims begins on page 2 of this paper.

Remarks/Arguments begin on page 7 of this paper.

Please amend the claims as follows. This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

Claims 1-16 (previously cancelled)

Claim 17 (previously amended): A wafer preparation module, comprising:
an enclosure containing wafer engaging rollers, the wafer engaging rollers being oriented at an angle, the angle configured to be between 0° to 90°, the wafer engaging rollers designed to spin a wafer at the angle during preparation.

Claim 18 (original): A wafer preparation module as recited in claim 17, wherein the preparation includes one of rinsing, cleaning, drying, scrubbing, and megasonic fluid application.

Claim 19 (original): A wafer preparation module as recited in claim 17, further comprising:

at least one cleaner dispenser configured to apply a fluid to a surface of the wafer during at least part of the preparation.

Claim 20 (original): A wafer preparation module as recited in claim 17, further comprising:

a nozzle configured to apply a gas flow toward at least one of wafer engaging rollers.

Claim 21 (original): A wafer preparation module as recited in claim 17, further comprising:

a megasonic spray assembly for applying a megasonic spray to a surface of the wafer.

Claim 22 (original): A wafer preparation module as recited in claim 17, wherein at least one of the wafer engaging rollers is a drive roller.

Claim 23 (original): A spin, rinse, and dry module comprising:

an enclosure having an outer wall, the outerwall being configured to include a window therein, the window being defined within the outerwall so as to create a process angle with a horizontal plane;

a pair of drive rollers defined within the enclosure, the drive rollers being configured to spin a substrate to be processed while engaging the substrate to be processed; and

an engaging roller defined within the enclosure, the engaging roller configured to engage the substrate to be processed, the engaging roller and the pair of drive rollers configured to engage the substrate to be processed such that the substrate to be processed creates an angle with the horizontal plane that is substantially equivalent to the process angle.

Claim 24 (previously amended): A spin, rinse, and dry module as recited in claim 23, further comprising:

a cleaner dispenser defined within the enclosure, the cleaner dispenser being configured to clean a top surface and a bottom surface of the substrate to be processed.

Claim 25 (original): A spin, rinse, and dry module as recited in claim 23, further comprising:

a megasonic assembly defined within the enclosure, the megasonic assembly being configured to be applied to a top surface and a bottom surface of the substrate to be processed.

Claim 26 (previously amended): A spin, rinse, and dry module as recited in claim 23, further comprising:

a plurality of gas blow nozzles defined within an inner wall of the enclosure, at least one gas blow nozzle being configured to dispense a first gas onto each of the drive rollers and the engaging roller.

Claim 27 (original): A spin, rinse, and dry module as recited in claim 23, further comprising:

a plurality of holes defined within an inner wall of the enclosure so as to introduce a second gas into the enclosure, the second gas being configured to substantially evenly dry a top surface and a bottom surface of the substrate to be processed.

Claim 28 (previously added): A wafer preparation module, comprising:

an enclosure containing wafer engaging rollers, the wafer engaging rollers being oriented at an angle, the wafer engaging rollers designed to spin a wafer at an angle during preparation; and

a nozzle configured to apply a gas flow toward at least one of wafer engaging rollers.

Claim 29 (previously added): A spin, rinse, and dry module comprising:

an enclosure having an outer wall, the outerwall being configured to include a window therein, the window being defined within the outerwall so as to create a process angle with a horizontal plane;

a pair of drive rollers defined within the enclosure, the drive rollers being configured to spin a substrate to be processed while engaging the substrate to be processed;

an engaging roller defined within the enclosure, the engaging roller configured to engage the substrate to be processed, the engaging roller and the pair of drive rollers configured to engage the substrate to be processed such that the substrate to be processed creates an angle with the horizontal plane that is substantially equivalent to the process angle; and

a plurality of gas blow nozzles defined within an inner wall of the enclosure, at least one gas blow nozzle being configured to dispense a first gas onto each of the drive rollers and the engaging roller.

Claim 30 (previously added): A spin, rinse, and dry module comprising:

an enclosure having an outer wall, the outerwall being configured to include a window therein, the window being defined within the outerwall so as to create a process angle with a horizontal plane;

a pair of drive rollers defined within the enclosure, the drive rollers being configured to spin a substrate to be processed while engaging the substrate to be processed;

an engaging roller defined within the enclosure, the engaging roller configured to engage the substrate to be processed, the engaging roller and the pair of drive rollers configured to engage the substrate to be processed such that the substrate to be processed creates an angle with the horizontal plane that is substantially equivalent to the process angle; and

a plurality of holes defined within an inner wall of the enclosure so as to introduce a second gas into the enclosure, the second gas being configured to substantially evenly dry a top surface and a bottom surface of the substrate to be processed.

Claim 31 (previously amended): A wafer preparation module, comprising:

an enclosure containing wafer engaging rollers, the wafer engaging rollers being suspended at an angle, the wafer engaging rollers designed to spin a wafer at an angle during preparation, the enclosure further having an inner wall containing a plurality of holes defined therein, the plurality of holes being configured to introduce a gas into the enclosure, the gas being configured to substantially evenly dry a top surface and a bottom surface of the wafer to be processed.

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AF 11700
PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

R. Treur

Application No: 09/823,813

Filed: March 30, 2001

For: ANGULAR SPIN, RINSE, AND DRY MODULE
AND METHODS FOR MAKING AND
IMPLEMENTING THE SAME

Attorney Docket No: LAM2P247

Examiner: F. L. Stinson

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Signed:

Courtney F. Yadegar

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Mail Stop: AF

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

Transmitted herewith is a Request for Reconsideration in the above-identified application.

The fee has been calculated as shown below.

	Claims Remaining After <u>Amendment</u>	Highest Previously <u>Paid For</u>	Present <u>Extra</u>	SMALL ENTITY <u>RATE FEE</u>	OR	LARGE ENTITY <u>RATE FEE</u>
TOTAL CLAIMS	<u>15</u> -	<u>15</u>	<u>00</u>	X09 = \$	OR	X18 = \$
INDEP CLAIMS	<u>06</u> -	<u>06</u>	<u>00</u>	X43 = \$	OR	X86 = \$
[] Multiple Dependent Claim Present and Fee Not Previously Paid				\$145		\$290
TOTAL				\$_____		\$_____

- ☐ Applicant(s) hereby petition for a _____ month(s) extension of time to respond to the outstanding Office Action.
- ☒ Applicant(s) believe that no (additional) Extension of Time is required; however, if it is determined that such an extension is required, Applicant(s) hereby petition that such an extension be granted and authorize the Commissioner to charge the required fees for an Extension of Time under 37 CFR 1.136 to Deposit Account No. 50-0805.
- ☐ Enclosed is our Check No. _____ in the amount of \$_____ to cover the additional claim fee and/or extension of time fees.
- ☒ If the required fees are missing or any additional fees are required to facilitate filing the enclosed response, please charge such fees or credit any overpayment to Deposit Account No. 50-0805 (Order No. LAM2P247). A copy of this sheet is enclosed.

Respectfully submitted,
MARTINE & PENILLA, LLP

Fariba Yadegar-Bandari, Esq.
Registration No. 53,805710 Lakeway Drive, Suite 170
Sunnyvale, CA 94085
Telephone: (408) 749-6900
Customer Number 25920